

## **ABSTRACT**

A three-dimensional stacked semiconductor package device includes first and second semiconductor package devices and a conductive bond. The first device includes a first insulative housing, a first semiconductor chip and a first lead that is bent outside the first  
5 insulative housing. The second device includes a second insulative housing, a second semiconductor chip and a second lead that is flat outside the second insulative housing. The conductive bond contacts and electrically connects the leads.